

PATENT ABSTRACTS OF JAPAN

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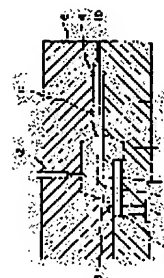
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(54) MANUFACTURE OF SEMICONDUCTOR DEVICE

(57)Abstract:

PURPOSE: To prevent resin burrs by a method wherein a predetermined area to be exposed on a side of a lead frame is masked, then is sealed with resin, and the masking is released when a part of one side of the lead frame is sealed with resin in a state exposed from the sealing material.

CONSTITUTION: In the rear side of a substrate 2 on which a semiconductor element 3 is mounted, a masked lead frame 1 is housed in a die cavity made of an upper type 6 and a lower type 7. At this time, the lead frame 1 is placed in the die so that a masking tape 8 is closely contacted with a cavity bottom surface 9. A guide pin 13 is inserted into a hole provided in the substrate 2 so as to fix the position of the lead frame 1. Resin is injected from a runner section 10 through an injection port 11 so that the substrate 2, the semiconductor element 3, the end of the lead 4, and a bonding wire 5 are integrally sealed with resin, then it is removed from the die with an ejector pin 12. Next, when the masking tape 8 is released from the substrate 2, the resin burrs 15 are removed together with the masking tape 8.



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